Revision A October 2001—First Printing (ECN released)

## PUBLISHED BY

Publications Department Lam Research Corporation 4650 Cushing Parkway Fremont, California 94538-6470 E-mail: pubs@lamrc.com

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Part Number: 405-240309-001

## 2300<sup>™</sup> Process Module Facility

PM BOM Version 571-800096-002 2300 Software Version 1.4.3 System Version 2300

Revision A October 2001

## 2300 Process Module Facility Legend:

This manual combines into one manual the process module facility information from the following process module types: 2300 Metal, Silicon, and Exelan. This manual replaces all previous process module type manuals.

## **Contents**

253-800096-001, Revision D, 300MM TCP PM Facility Specification 1
253-810068-001, Revision J, 300MM Facility Requirements Drawing 7
251-800096-001, Revision C, 300MM PM P&ID Diagram 21
224-800096-001, Revision D, 300MM Process Module Interconnect Diagram 27
224-800096-002, Revision E, 300MM PM AC DC Interconnect Diagram 29
224-800096-003, Revision D, 300MM PM Heaters Interconnect Diagram 31
224-800096-004, Revision D, 300MM PM Thermocouples Interconnect Diagram 33
224-800096-005, Revision D, 300MM PM Overtemp Interconnect Diagram 35
224-800096-006, Revision E, 300MM PM Communications Interconnect Diagram 37
224-800096-007, Revision E, 300MM PM Hardware Interlock Interconnect Diagram 39
224-800096-008, Revision E, 300MM PM Node 1 Interconnect Diagram 41
224-800096-009, Revision E, 300MM PM Node 5 Interconnect Diagram 43
224-800096-402, Revision A, DFC PM AC DC Distribution Interconnect Diagram 45
224-800096-406, Revision A, DFC PM Communication Interconnect Diagram 47
224-800096-407, Revision A, DFC PM Interlock Interconnect Diagram 49
224-800096-408, Revision A, DFC PM Node 1 Interconnect Diagram 51
224-800096-409, Revision A, DFC Node 5 Interconnect Diagram 53
253-802968-002, Revision B, Installation Template for 2300 Process Module 55















































































